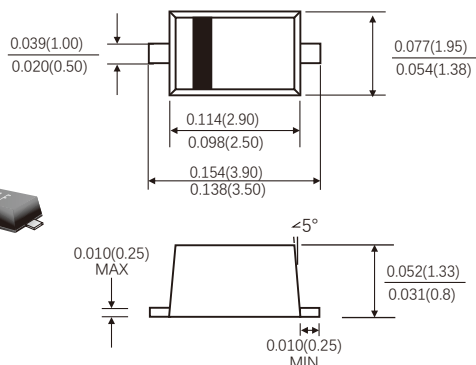


## Features

- Very low profile package
- Ideal for automated placement
- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,low forward voltage drop
- High surge capability
- Meets MSL Level 1,per J-STD-020,LF maximum peak of 260°C
- Component in accordance to RoHS 2015/863/EU



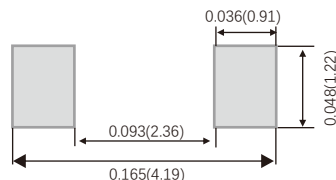
## SOD-123FL



## Mechanical Data

- Case: Flat lead SOD-123FL small outline plastic package
- Molding compound meets UL 94 V-0 flammability rating
- Terminals: solderable per J-STD-002 and JESD22-B102
- Polarity: color band denotes cathode end
- Mounting Position: Any
- Weight: 8.85 mg(approximately)

## Suggested PAD Layout



Dimensions in inches and (millimeters)

## Typical Applications

For use in low voltage ,high frequency inverters ,DC/DC converters, free wheeling ,and polarity protection applications

## Maximum Ratings

(Ratings at 25°C ambient temperature unless otherwise specified )

Parameter	Symbol	Value	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	60	V
Maximum average forward rectified current (see fig.1)	$I_{F(AV)}$	1.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method at rated TL)	$I_{FSM}$	40	A
Operating junction temperature range	$T_J$	-55 to +150	°C
Storage temperature range	$T_{STG}$	-55 to +150	°C

## Electrical Characteristics (T<sub>a</sub>=25°C Unless Otherwise Noted)

Parameter	Test Conditions		Symbol	Typ.	Max.	Unit
Instantaneous forward voltage	I <sub>F</sub> =1.0A	T <sub>J</sub> =25°C	V <sub>F</sub> <sup>1)</sup>	0.60	0.65	V
		T <sub>J</sub> =100°C		0.57	-	
		T <sub>J</sub> =125°C		0.54	-	
Reverse current	V <sub>R</sub> =60V	T <sub>J</sub> =25°C	I <sub>R</sub> <sup>2)</sup>	14	40	μA
		T <sub>J</sub> =100°C		-	5.0	mA
		T <sub>J</sub> =125°C		-	20	
Typical junction capacitance	4V,1MHz		C <sub>J</sub>	45		pF

Notes: 1.Pulse test: 300 μs pulse width,1% duty cycle

2.Pulse test: pulse width ≤40ms

## Thermal Characteristics

Parameter	Symbol	K16	Unit
Typical thermal resistance <sup>3)</sup>	R <sub>θJA</sub>	206.0	°C/W
	R <sub>θJL</sub>	118.0	

3.PCB Mounted with The Suggested PAD Size

## Available Pack Information

Product code	Pack	Reel Size (mm)	Quantity (pcs/reel)	Box Size L×W×H (mm)	Quantity (reel/box)	Carton Size L×W×H (mm)	Quantity (box/carton)
K16-SOD-123FL	T/R	Φ330	7500	330×35×333	2	364×364×360	8

Fig.1-Forward Current Derating Curve

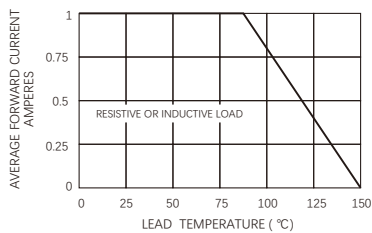


Fig.2-Maximum Non-repetitive Peak Forward Surge Current

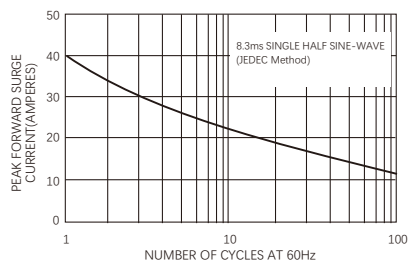


Fig.3-Typical Instantaneous Forward Characteristics

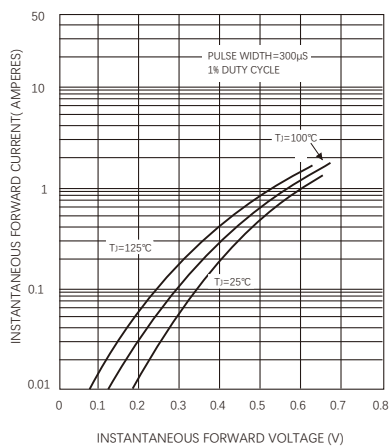


Fig.4-Typical Reverse Characteristics

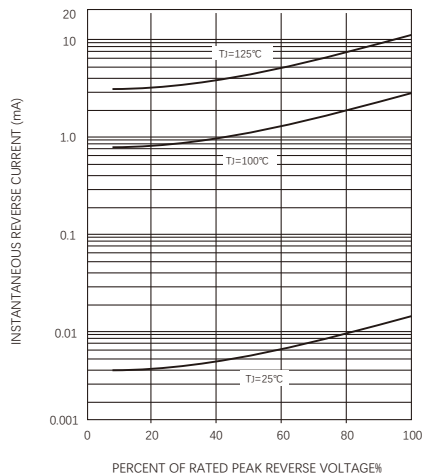
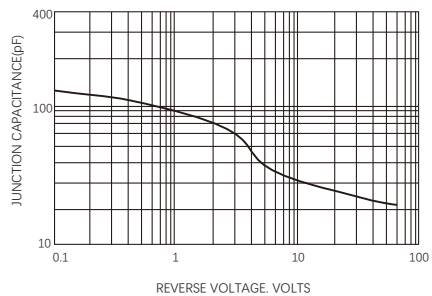


Fig.5-Typical Junction Capacitance



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